



TECHNICAL DATA SHEET

PAI-3663 HAL Liquid Flux

PAI - 3663 is Water Soluble Organic Liquid Flux specially designed for Fabricating Printed Circuit Boards in a vertical Hot Air Leveling Equipment. PAI-3663 Non-splattering characteristics reduce Solder consumption/waste and draws consistent Soldering performance. PAI-3663 Moderate Activation levels makes most suitable to apply where minimal pre-cleaning Process is in place. PAI- 3663 high viscous Solid content also helps to apply in Processes where longer Dwell Time required.

ADVANTAGES OF USING PAI 3663

PAI-3663 is specially formulated to meet stringent conditions and improvements on Assembly and Cleaning Processes. As a result, PAI-3663 derived numerous advantages as compared to normal Fluxes, which are outlined below.

1. Reduced Halide
2. Moderate Activation
3. Easy to use
4. Minimum Pre-cleaning
5. Excellent Wetting Property
6. Residues are Soluble with Water
7. Reduces amount of Water used for Cleaning
8. PCBs glare reflects at Post-Cleaning as same as that reflects at Pre Cleaning
9. Draws high SIR Test values at Post Cleaning
10. Minimized corrosive to fingers on Soldering Machines
11. High definition par to Economy

APPLICATION INFORMATION

PAI-3663 Liquid Flux is applicable to any of existing Vertical HAL Soldering Machines used in the Industry today. Application shall be in Dip & Spray methods.

FLUX QUALITY

Periodic monitoring of Specific Gravity with Hydrometer or Automatic Density Sensor System and addition of an appropriate amount of T.3663 is necessary to ascertain consistent Soldering results. In Time, debris and contaminates will accumulate in the Flux. These contaminations will affect the Quality of Flux, hence soldering results. For consistent Soldering performance, replace Flux periodically. Before replacing the Flux with fresh Liquid, Reservoir and Fluxing attachment should be thoroughly clean with water & dry cloth. During cleaning Process, it would be as good a time to clean both the Conveyor and HAL Machine Conveyor Fingers and Jigs from accumulated Flux Residue. Similar cleaning of Solder Pot is also recommended. After cleaning, rinse all relevant parts with suitable methods. Refill Flux reservoir with fresh Flux before resuming Soldering Process.

SAFETY AND STORAGE:

Keep Liquid carriers away from direct sunlight and source of ignition. Storage Temperature shall be between 10°C to 80°C. Avoid Eye and Skin contact by wearing Eye gears & Vinyl gloves of PPEs while handling liquid. Sufficient localized exhaust system should be there in place where vapor is generated.



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PHYSICAL PROPERTIES

SI No	Item	Specification
1	Model Number	PAI-3663
2	Type	Water Soluble
3	Physical State	Liquid
4	Color	Colorless to Lightly Yellow
5	Fillet Surface Appearance	Shiny
6	Fillet Size	Medium to Large
7	Solid Residue	Soluble in Water.
8	Specific Gravity at 25°C	1.14 (±0.005)
9	Flash Point (open cup)	None
10	Surface Insulation Resistance (At post cleaning)	1 x 10
11	PH (1%Soln in water)	>2.8
12	Density Reducer	T.3663
13	Standard Packing	20 liters carboy

Note: The above Specifications are particular for above model number. Alterations shall be made as per Specifications of an individual customer with proper measurement actions

For more details, please visit Our Website at www.persangalloy.com or write to us.



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